

# DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

Docket No. YOR920010216US1

As below named inventors, we hereby declare that:

Our residences, post office addresses and citizenships are as stated below next to our respective names.

We believe we are the original, and first joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## **HIGH DENSITY AREA ARRAY SOLDER MICROJOINING INTERCONNECT STRUCTURE AND FABRICATION METHOD**

the specification of which

(check one) XXX is attached hereto.

\_\_\_\_\_ was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_  
and was amended on \_\_\_\_\_ (if applicable).

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to us to be material to the patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56.

We hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate(s) listed below and have also identified below any foreign application(s) for patent or inventor's certificate(s) having a filing date before that of the application on which priority is claimed:

### Prior Foreign Application(s)

### Priority Claimed

_____ (Number)	_____ (Country)	_____ (Day/Mon/Year Filed)	____ Yes ____ No
_____ (Number)	_____ (Country)	_____ (Day/Mon/Year Filed)	____ Yes ____ No
_____ (Number)	_____ (Country)	_____ (Day/Mon/Year Filed)	____ Yes ____ No

We hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which

occurred between the filing date of the prior application and the national or PCT international filing date of this application:

_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status - patent, pend., abandon.)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status - patent, pend., abandon.)

POWER OF ATTORNEY: As named inventors, we hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

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We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are

punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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**GEORGE FREDERICK WALKER**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Magerlein et al.  
Serial No.: Not Yet Assigned  
Filed: Herewith  
For: HIGH DENSITY AREA ARRAY SOLDER MICROJOINING  
INTERCONNECT STRUCTURE AND FABRICATION METHOD  
Examiner: Not Yet Assigned  
Art Unit: Not Yet Assigned

Attorney Docket No.: YOR920010216US1

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Commissioner for Patents  
Washington, DC 20231

Dear Sir:

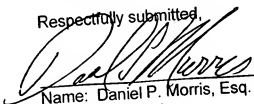
Please recognize Paul D. Greeley, Reg. No. 31,019 and Charles N.J. Ruggiero, Reg. No. 24,648 of the law firm Ohlandt, Greeley, Ruggiero & Perle, L.L.P. with offices at One Landmark Square, 10th Floor, Stamford, Connecticut 06901-2682, as an attorney, with full and complete powers to prosecute this patent application and to transact all business in the Patent and Trademark Office connected therewith.

Please continue to address all correspondence to:

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Respectfully submitted,

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